ABSTRACT

[0040] Cooling techniques to cool electronic devices in a computer system are disclosed. For one embodiment, the cooling technique utilizes a combination of an active cooling component with a passive cooling component. The active cooling component includes a heat exchanger, a pipe loop, and a pump. A liquid coolant is to extract heat from an electronic device and be transported by the pipe loop to the heat exchanger where the heat is rejected. The flow of the liquid coolant between the electronic device and the heat exchanger is enhanced by the pump. The passive cooling component includes a heat pipe. An evaporation end of the heat pipe is coupled to the electronic device to extract heat from the electronic device. A condensation end of the heat pipe is coupled to the heat exchanger to condense vapor in the heat pipe.